

R1LP0408D Series

4Mb Advanced LPSRAM (512-kword × 8-bit)

R10DS0274EJ0200 Rev.2.00 2019.10.29

Description

The R1LP0408D Series is a family of 4-Mbit static RAMs organized 512-kword × 8-bit, fabricated by Renesas's high-performance CMOS and TFT technologies. The R1LP0408D Series has realized higher density, higher performance and low power consumption. The R1LP0408D Series offers low power standby power dissipation; therefore, it is suitable for battery backup systems. It is offered in 32-pin SOP and 32-pin TSOP.

Features

Single 5V supply: 4.5V to 5.5VAccess time: 55ns (max.)

Power dissipation:
— Standby: 4µW (typ.)

Equal access and cycle times

• Common data input and output

— Three state output

Directly TTL compatible
All inputs and outputs

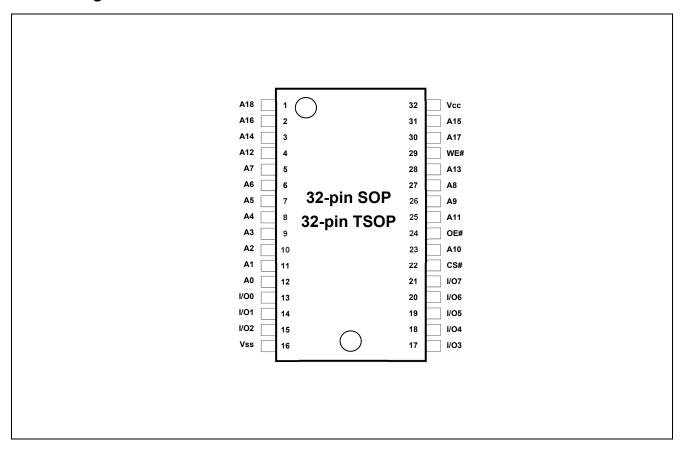
• Battery backup operation

Ordering Information

Orderable part name	Access time	Temperature range	Package	Shipping container
R1LP0408DSP-5SI#B*			525-mil 32-pin	Tube (Magazine)
R1LP0408DSP-5SI#S*	55	40 .05%	plastic SOP	Embossed tape
R1LP0408DSB-5SI#B*	55 ns	-40 ~ +85°C	400-mil 32-pin	Tray
R1LP0408DSB-5SI#S*			plastic TSOP (II)	Embossed tape

Note 1. * = Revision code for Assembly site change, etc. (* = 0, 1, etc.)

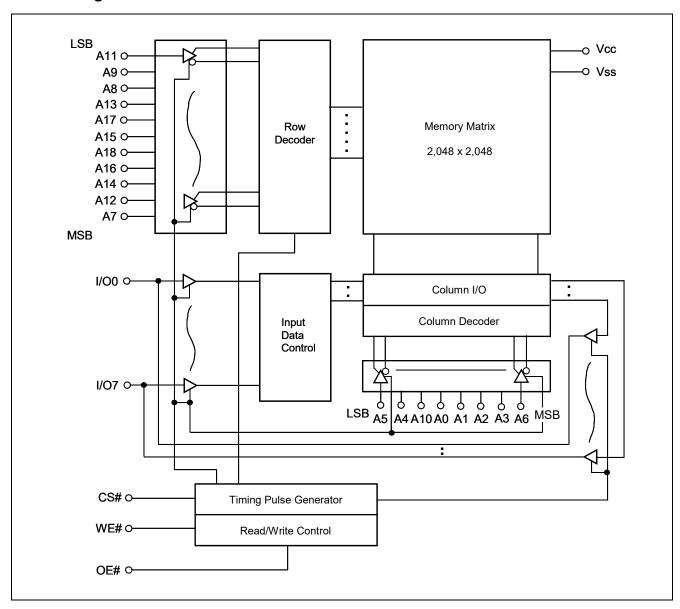
Pin Arrangement



Pin Description

Pin name	Function					
Vcc	Power supply					
Vss	Ground					
A0 to A18	Address input					
I/O0 to I/O7	Data input/output					
CS#	Chip select					
WE#	Write enable					
OE#	Output enable					

Block Diagram



Operation Table

WE#	CS#	OE#	Mode	Vcc current	I/O0 to I/O7	Ref. cycle
×	Н	×	Not selected	I _{SB} , I _{SB1}	High-Z	ı
Н	L	Н	Output disable	lcc	High-Z	ı
Н	L	L	Read	Icc	Dout	Read cycle
L	L	Н	Write	Icc	Din	Write cycle (1)
L	L	L	Write	lcc	Din	Write cycle (2)

Note 1. H: V_{IH} L:V_{IL} ×: V_{IH} or V_{IL}

Absolute Maximum Ratings

Parameter	Symbol	Value	unit
Power supply voltage relative to Vss	Vcc	-0.5 to +7.0	V
Terminal voltage on any pin relative to Vss	V _T	-0.5*1 to Vcc+0.3*2	V
Power dissipation	PT	0.7	W
Operation temperature	Topr	-40 to +85	°C
Storage temperature range	Tstg	-65 to 150	°C
Storage temperature range under bias	Tbias	-40 to +85	°C

Note 1. -3.0V for pulse ≤ 30ns (full width at half maximum)

2. Maximum voltage is +7.0V.

DC Operating Conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	4.5	5.0	5.5	V	
	Vss	0	0	0	V	
Input high voltage	V _{IH}	2.2	_	Vcc+0.3	V	
Input low voltage	VIL	-0.3	-	0.8	V	1
Ambient temperature range	Та	-40	_	+85	°C	

Note 1. -3.0V for pulse ≤ 30ns (full width at half maximum)

DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit		Test conditions		
Input leakage current	Iu	_	_	1	μА	Vin = Vss to Vcc			
Output leakage current	 Lo	_	_	1	μА		or OE# =V _{IH} ,		
	11501			•	pa (VI/O =Vs			
Operating current	Icc	_	5*1	10	mA	CS# =V _{IL}			
							V _{IH} /V _{IL} , II/O = 0mA		
Average operating current	I _{CC1}	_	15 ^{*1}	25	mA	-	e, duty =100%, II/O = 0mA, , Others = V _{IH} /V _{IL}		
							μs, duty =100%, II/O = 0mA,		
	I _{CC2}	_	3 ^{*1}	5	mA	CS# ≤ 0.:	•		
							V _{IH} ≥ Vcc-0.2V, V _{IL} ≤ 0.2V		
Standby current	I _{SB}	_	0.1 ^{*1}	0.5	mA	CS# =V _{IH} ,			
						Others =	Vss to Vcc		
Standby current		_	0.8*1	2.5	μА	~+25°C			
		-	1 ^{*2}	3	μА	~+40°C	Vin = Vss to Vcc,		
	I _{SB1}	_	_	8	μА	~+70°C	CS# ≥ Vcc-0.2V		
		_	_	10	μА	~+85°C			
Output high voltage	Vон	2.4	_	_	V	I _{OH} = -1mA			
	V _{OH2}	Vcc-0.5	_	_	V	I _{OH} = -0.1mA			
Output low voltage	Vol	_	_	0.4	V	I _{OL} = 2.1r	I _{OL} = 2.1mA		

Note 1. Typical parameter indicates the value for the center of distribution at 5.0V (Ta=25°C), and not 100% tested.

Capacitance

 $(Vcc = 4.5V \sim 5.5V, f = 1MHz, Ta = -40 \sim +85^{\circ}C)$

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions	Note
Input capacitance	C in	_	_	8	pF	Vin =0V	1
Input / output capacitance	C 1/0	_	_	10	pF	VI/O =0V	1

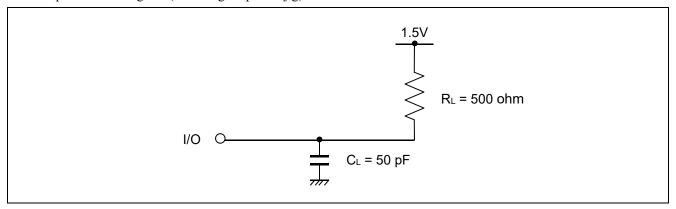
Note 1. This parameter is sampled and not 100% tested.

^{2.} Typical parameter indicates the value for the center of distribution at 5.0V (Ta=40°C), and not 100% tested.

AC Characteristics

Test Conditions (Vcc = $4.5V \sim 5.5V$, Ta = $-40 \sim +85$ °C)

- Input pulse levels: VIL = 0.4V, VIH = 2.4V
- Input rise and fall time: 5ns
- Input and output timing reference level: 1.5V
- Output load: See figures (Including scope and jig)



Read Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Read cycle time	t _{RC}	55	_	ns	
Address access time	t _{AA}	_	55	ns	
Chip select access time	t _{ACS}	_	55	ns	
Output enable to output valid	toe	_	25	ns	
Chip select to output in low-Z	tclz	10	ı	ns	2
Output enable to output in low-Z	tolz	5	-	ns	2
Chip deselect to output in high-Z	tcHZ	0	20	ns	1,2
Output disable to output in high-Z	tonz	0	20	ns	1,2
Output hold from address change	tон	10	_	ns	

Write Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Write cycle time	twc	55	_	ns	
Chip select to end of write	tcw	50	ı	ns	4
Address setup time	t _{AS}	0	ı	ns	5
Address valid to end of write	t _{AW}	50	ı	ns	
Write pulse width	twp	40	ı	ns	3,12
Write recovery time	twR	0	ı	ns	6
Write to output in high-Z	twnz	0	20	ns	1,2,7
Data to write time overlap	t _{DW}	25	_	ns	
Data hold from write time	t _{DH}	0	_	ns	
Output enable from end of write	tow	5		ns	2
Output disable to output in high-Z	tонz	0	20	ns	1,2,7

Note

- 1. t_{CHZ}, t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (twp) of a low CS# and a low WE#.

A write begins at the later transition of CS# going low or WE# going low.

A write ends at the earlier transition of CS# going high or WE# going high.

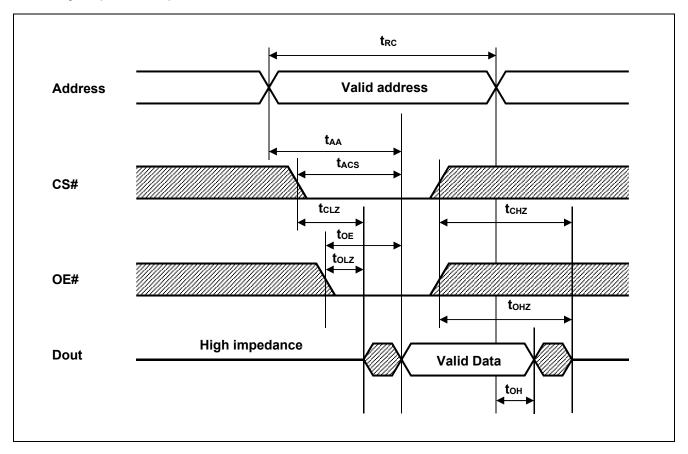
twp is measured from the beginning of write to the end of write.

- 4. t_{CW} is measured from CS# going low to end of write.
- 5. t_{AS} is measured the address valid to the beginning of write.
- 6. two is measured from the earlier of WE# or CS# going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. If the CS# low transition occurs simultaneously with the WE# low transition or after the WE# transition, the output remain in a high impedance state.
- 9. Dout is the same phase of the write data of this write cycle.
- 10. Dout is the read data of next address.
- 11. If CS# is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 12. In the write cycle with OE# low fixed, twp must satisfy the following equation to avoid a problem of data bus contention.

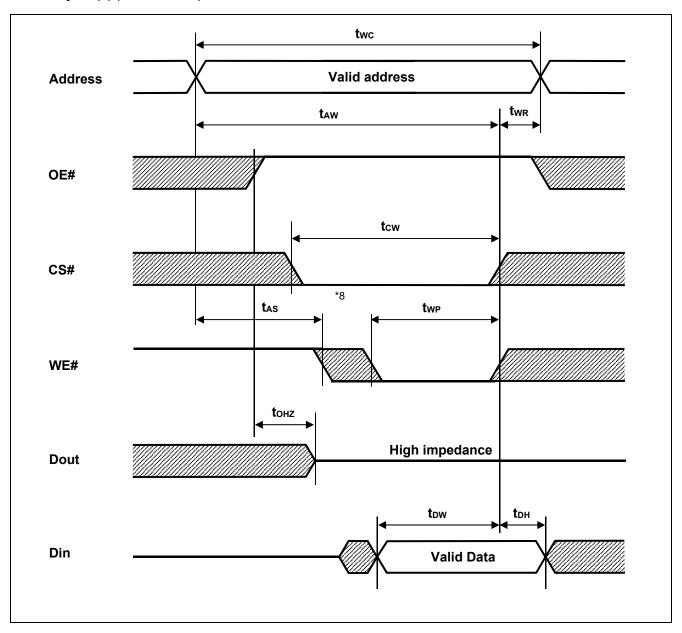
twp ≥ t_{DW} min + t_{WHZ} max

Timing Waveforms

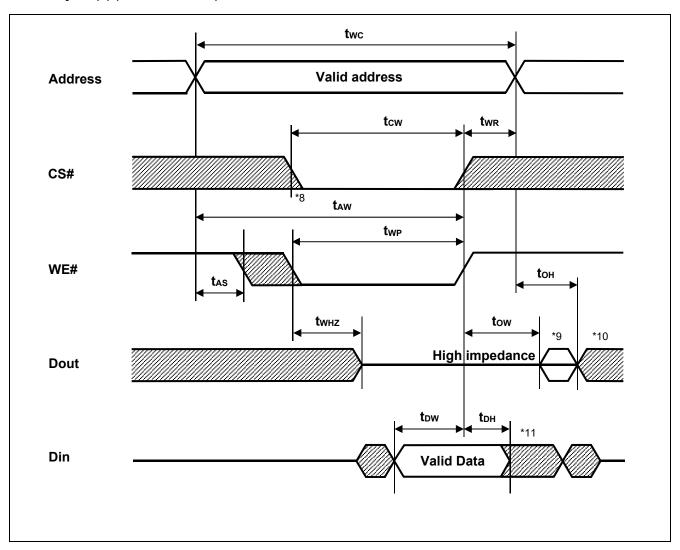
Read Cycle (WE# = V_{IH})



Write Cycle (1) (OE# CLOCK)



Write Cycle (2) (OE# Low Fixed)



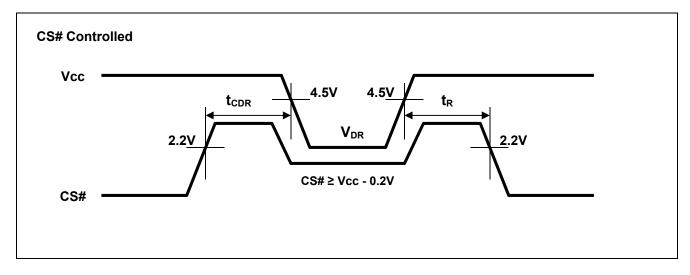
Low Vcc Data Retention Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions*3		
V _{CC} for data retention	V_{DR}	2.0		5.5	>	Vin ≥ 0V, CS# ≥ Vcc	c-0.2V	
Data retention current	Iccdr	_	0.8*1	2.5	μА	~+25°C		
		_	1* ²	3	μΑ	~+40°C	Vcc=3.0V, Vin ≥ 0V,	
		_	_	8	μА	~+70°C	CS# ≥ Vcc-0.2V	
		_	_	10	μА	~+85°C		
Chip deselect time to data retention	t _{CDR}	0	_	-	ns	Con materials was reformed		
Operation recovery time	t _R	5	_	_	ms	See retention waveform.		

Note

- 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta=25°C), and not 100% tested.
- 2. Typical parameter indicates the value for the center of distribution at 3.0V (Ta=40°C), and not 100% tested.
- 3. CS# controls address buffer, WE# buffer, OE# buffer and Din buffer. If data retention mode, Vin levels (address, WE#, OE#, I/O) can be in the high impedance state.

Low Vcc Data Retention Timing Waveforms



R1LP0408D Series Data Sheet

		Description				
Rev.	Date	Page	Summary			
1.00	2017.1.27	-	First Edition issued			
2.00	2019.10.29	p.1	p.1 Revised orderable part name information.			

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